

IN THE CLAIMS

Please cancel claims 3 and 4 without prejudice.

Please amend the following claims which are pending in the present application:

1. (Currently amended) An electronic package, comprising:
a substrate having at least (i) a first resilient layer ~~with a~~, (ii) a second resilient layer in a plane parallel to and above the first resilient layer, the first and second resilient layers respectively having first and second substantially parallel spaced edges, and (iii) a flexible layer which is bent, with the first and second edges promoting where the flexible layer is bent;
a plurality of traces supported by the substrate and extending from a first portion to a second portion on respectively first and second opposite sides of the edge; and
at least a first electronic device, carrying an integrated circuit, mounted to the substrate on the first side of the edge.
2. (Original) The electronic package of claim 1, further comprising:
a second electronic device mounted to the substrate on the second side of the edge.

3-4. (Cancelled)

5. (Original) An electronic package, comprising:

a substrate having a first portion, a second portion, and a fold portion between the first and second portions, the substrate including at least a first resilient layer forming part of the first portion and a flexible layer, the flexible layer being bent so that the second portion is in a plane above and substantially parallel to the first portion, with a first edge of the first resilient layer promoting where the flexible layer is bent;

a plurality of first contacts exposed on an upper side of the first portion;

a plurality of terminals exposed on a lower side of the first portion;

a plurality of vias in the first portion interconnecting at least some of the first contacts with at least some of the terminals;

a plurality of second exposed contacts on the second portion; and

a plurality of traces supported by the substrate and extending from the first portion across the fold portion to the second portion to the second contacts.

6. (Original) The electronic package of claim 5, wherein the substrate includes a second resilient layer forming part of the second portion, a second edge of the second portion promoting where the flexible layer is bent, the fold region being between the first and second edges.

7. (Original) The electronic package of claim 6, wherein the edges create stress concentrations in the fold portion of the flexible layer.

8. (Original) The electronic package of claim 5, wherein at least one of the traces interconnects one of the first contacts with one of the second contacts.
9. (Original) The electronic package of claim 8, wherein at least one of the traces interconnects one of the terminals with one of the second contacts.
10. (Original) The electronic package of claim 5, wherein at least one of the traces interconnects one of the terminals with one of the second contacts.
11. (Original) The electronic package of claim 5, wherein the first resilient layer is made of metal.
12. (Original) The electronic package of claim 11, wherein the first resilient layer is electrically connected to one of the terminals.
13. (Original) The electronic package of claim 5, further comprising:
at least a first electronic device, carrying an integrated circuit, mounted to the first portion and having lands that are electrically connected to the first contacts.
14. (Original) The electronic package of claim 13, further comprising:

at least a second electronic device, carrying an integrated circuit, mounted to the second portion and having lands that are electrically connected to the second contacts.

15. (Original) An electronic package, comprising:

a substrate having a first portion, a second portion, and a fold portion between the first and second portions, the substrate including at least a first resilient layer forming part of the first portion, a second resilient layer forming part of the second portion, and a flexible layer, the flexible layer being bent so that the second portion is in a plane above and substantially parallel to the first portion, with a first edge of the first resilient layer promoting where the flexible layer is bent and a second edge of the second portion promoting where the flexible layer is bent, the fold region being between the first and second edges;

a plurality of first contacts exposed on an upper side of the first portion;

at least a first electronic device, carrying an integrated circuit, mounted to the first portion and having lands that are electrically connected to the first contacts.

a plurality of terminals exposed on a lower side of the first portion;

a plurality of vias in the first portion interconnecting at least some of the first contacts with at least some of the terminals;

a plurality of second exposed contacts on the second portion;

at least a second electronic device, carrying an integrated circuit, mounted

to the second portion and having lands that are electrically connected to the second contacts; and

a plurality of traces supported by the substrate and extending from the first portion across the fold portion to the second portion to the second contacts.

16. (Original) The electronic package of claim 15, wherein the first resilient layer is made of metal.

17. (Original) The electronic package of claim 16, wherein the first resilient layer is electrically connected to one of the terminals.

18-20. (Cancelled)